

# NTF5P03T3

Preferred Device

## Power MOSFET 5.2 Amps, 30 Volts

P-Channel SOT-223

### Features

- Ultra Low  $R_{DS(on)}$
- Higher Efficiency Extending Battery Life
- Logic Level Gate Drive
- Miniature SOT-223 Surface Mount Package
- Avalanche Energy Specified
- Pb-Free Package is Available

### Applications

- DC-DC Converters
- Power Management
- Motor Controls
- Inductive Loads
- Replaces MMFT5P03HD

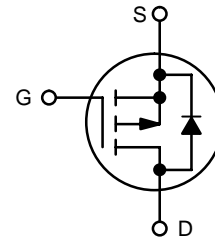


**ON Semiconductor**<sup>®</sup>

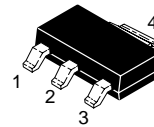
<http://onsemi.com>

**5.2 AMPERES, 30 VOLTS**

**$R_{DS(on)} = 100 \text{ m}\Omega$**

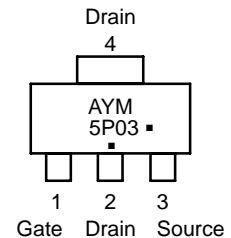


P-Channel MOSFET



SOT-223  
CASE 318E  
STYLE 3

### MARKING DIAGRAM & PIN ASSIGNMENT



- A = Assembly Location
- Y = Year
- M = Date Code
- 5P03 = Specific Device Code
- = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTF5P03T3	SOT-223	4000/Tape & Reel
NTF5P03T3G	SOT-223 (Pb-Free)	4000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

## NTF5P03T3

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Negative sign for P-Channel devices omitted for clarity

Rating		Symbol	Max	Unit
Drain-to-Source Voltage		$V_{DSS}$	-30	V
Drain-to-Gate Voltage ( $R_{GS} = 1.0\text{ M}\Omega$ )		$V_{DGR}$	-30	V
Gate-to-Source Voltage – Continuous		$V_{GS}$	$\pm 20$	V
1 sq in FR-4 or G-10 PCB  10 seconds	Thermal Resistance – Junction to Ambient	$R_{THJA}$	40	$^\circ\text{C/W}$
	Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$P_D$	3.13	Watts
	Linear Derating Factor		25	$\text{mW}/^\circ\text{C}$
	Drain Current – Continuous @ $T_A = 25^\circ\text{C}$	$I_D$	-5.2	A
10 seconds	Continuous @ $T_A = 70^\circ\text{C}$	$I_D$	-4.1	A
	Pulsed Drain Current (Note 1)	$I_{DM}$	-26	A
	Thermal Resistance – Junction to Ambient	$R_{THJA}$	80	$^\circ\text{C/W}$
Minimum FR-4 or G-10 PCB  10 seconds	Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$P_D$	1.56	Watts
	Linear Derating Factor		12.5	$\text{mW}/^\circ\text{C}$
	Drain Current – Continuous @ $T_A = 25^\circ\text{C}$	$I_D$	-3.7	A
	Continuous @ $T_A = 70^\circ\text{C}$	$I_D$	-2.9	A
10 seconds	Pulsed Drain Current (Note 1)	$I_{DM}$	-19	A
	Operating and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	$^\circ\text{C}$
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ\text{C}$ ( $V_{DD} = -30\text{ Vdc}$ , $V_{GS} = -10\text{ Vdc}$ , Peak $I_L = -12\text{ Apk}$ , $L = 3.5\text{ mH}$ , $R_G = 25\ \Omega$ )		$E_{AS}$	250	mJ

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Repetitive rating; pulse width limited by maximum junction temperature.

# NTF5P03T3

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (Cpk ≥ 2.0) (Notes 2 and 4) (V <sub>GS</sub> = 0 Vdc, I <sub>D</sub> = -0.25 μAdc) Temperature Coefficient (Positive)	V <sub>(BR)DSS</sub>	-30	-	-	Vdc
		-	-28	-	mV/°C
Zero Gate Voltage Drain Current (V <sub>DS</sub> = -24 Vdc, V <sub>GS</sub> = 0 Vdc) (V <sub>DS</sub> = -24 Vdc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 125°C)	I <sub>DSS</sub>	-	-	-1.0	μAdc
		-	-	-25	
Gate-Body Leakage Current (V <sub>GS</sub> = ± 20 Vdc, V <sub>DS</sub> = 0 Vdc)	I <sub>GSS</sub>	-	-	± 100	nAdc

### ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage (Cpk ≥ 2.0) (Notes 2 and 4) (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -0.25 μAdc) Threshold Temperature Coefficient (Negative)	V <sub>GS(th)</sub>	-1.0	-1.75	-3.0	Vdc
		-	3.5	-	mV/°C
Static Drain-to-Source On-Resistance (Cpk ≥ 2.0) (Notes 2 and 4) (V <sub>GS</sub> = -10 Vdc, I <sub>D</sub> = -5.2 Adc) (V <sub>GS</sub> = -4.5 Vdc, I <sub>D</sub> = -2.6 Adc)	R <sub>DS(on)</sub>	-	76	100	mΩ
			107	150	
Forward Transconductance (Note 2) (V <sub>DS</sub> = -15 Vdc, I <sub>D</sub> = -2.0 Adc)	g <sub>fs</sub>	2.0	3.9	-	Mhos

### DYNAMIC CHARACTERISTICS

Input Capacitance	(V <sub>DS</sub> = -25 Vdc, V <sub>GS</sub> = 0 V, f = 1.0 MHz)	C <sub>iss</sub>	-	500	950	pF
Output Capacitance		C <sub>oss</sub>	-	153	440	
Transfer Capacitance		C <sub>rss</sub>	-	58	140	

### SWITCHING CHARACTERISTICS (Note 3)

Turn-On Delay Time	(V <sub>DD</sub> = -15 Vdc, I <sub>D</sub> = -4.0 Adc, V <sub>GS</sub> = -10 Vdc, R <sub>G</sub> = 6.0 Ω) (Note 2)	t <sub>d(on)</sub>	-	10	24	ns
Rise Time		t <sub>r</sub>	-	33	48	
Turn-Off Delay Time		t <sub>d(off)</sub>	-	38	94	
Fall Time		t <sub>f</sub>	-	20	92	
Turn-On Delay Time	(V <sub>DD</sub> = -15 Vdc, I <sub>D</sub> = -2.0 Adc, V <sub>GS</sub> = -10 Vdc, R <sub>G</sub> = 6.0 Ω) (Note 2)	t <sub>d(on)</sub>	-	16	38	ns
Rise Time		t <sub>r</sub>	-	45	110	
Turn-Off Delay Time		t <sub>d(off)</sub>	-	23	60	
Fall Time		t <sub>f</sub>	-	24	80	
Gate Charge	(V <sub>DS</sub> = -24 Vdc, I <sub>D</sub> = -4.0 Adc, V <sub>GS</sub> = -10 Vdc) (Note 2)	Q <sub>T</sub>	-	15	38	nC
		Q <sub>1</sub>	-	1.6	-	
		Q <sub>2</sub>	-	3.5	-	
		Q <sub>3</sub>	-	2.6	-	

### SOURCE-DRAIN DIODE CHARACTERISTICS

Forward On-Voltage	(I <sub>S</sub> = -4.0 Adc, V <sub>GS</sub> = 0 Vdc) (I <sub>S</sub> = -4.0 Adc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 125°C) (Note 2)	V <sub>SD</sub>	-	-1.1	-1.5	Vdc
			-	-0.89	-	
Reverse Recovery Time	(I <sub>S</sub> = -4.0 Adc, V <sub>GS</sub> = 0 Vdc, di <sub>S</sub> /dt = 100 A/μs) (Note 2)	t <sub>rr</sub>	-	34	-	ns
		t <sub>a</sub>	-	20	-	
		t <sub>b</sub>	-	14	-	
Reverse Recovery Stored Charge		Q <sub>RR</sub>	-	0.036	-	μC

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
3. Switching characteristics are independent of operating junction temperatures.
4. Reflects typical values.

$$Cpk = \left| \frac{\text{Max limit} - \text{Typ}}{3 \times \text{SIGMA}} \right|$$

# NTF5P03T3

## TYPICAL ELECTRICAL CHARACTERISTICS

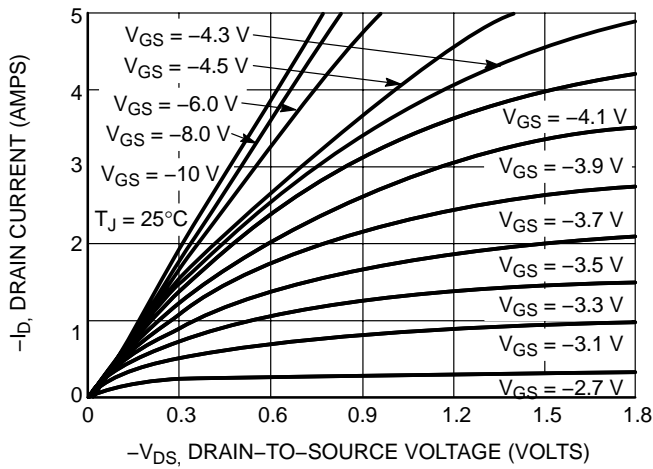


Figure 1. On-Region Characteristics

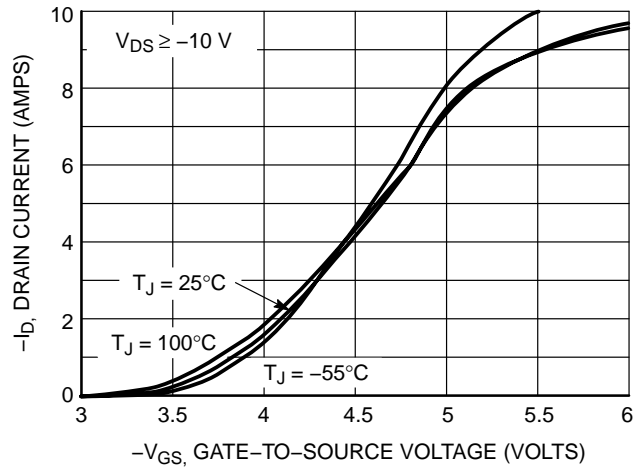


Figure 2. Transfer Characteristics

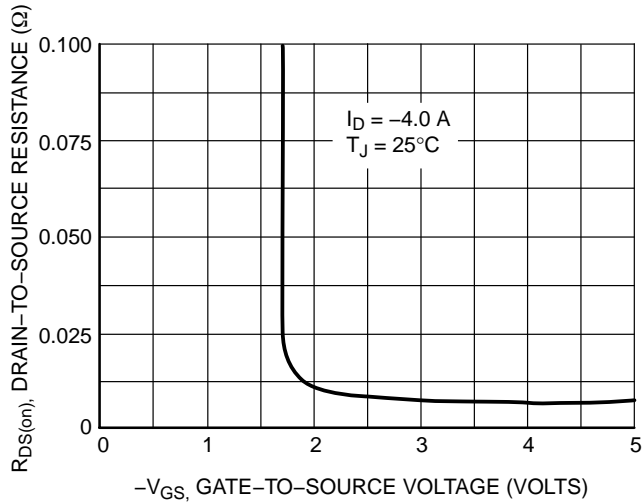


Figure 3. On-Resistance versus Gate-to-Source Voltage

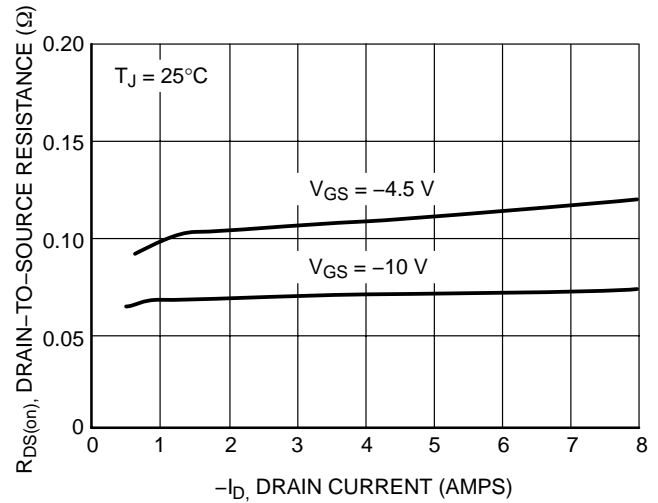


Figure 4. On-Resistance versus Drain Current and Gate Voltage

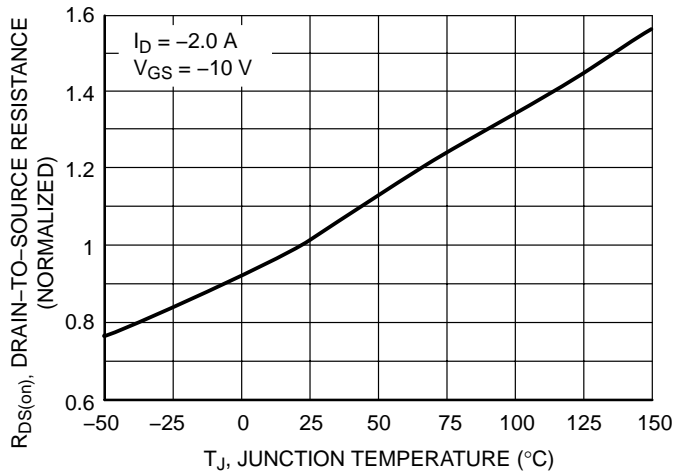


Figure 5. On-Resistance Variation with Temperature

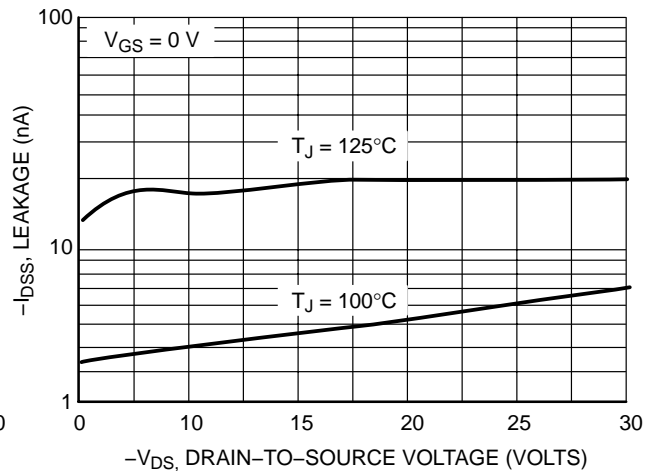


Figure 6. Drain-to-Source Leakage Current versus Voltage

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## TYPICAL ELECTRICAL CHARACTERISTICS

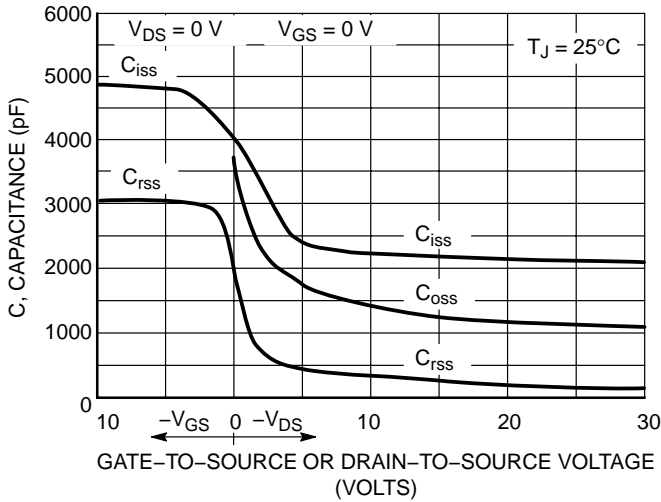


Figure 7. Capacitance Variation

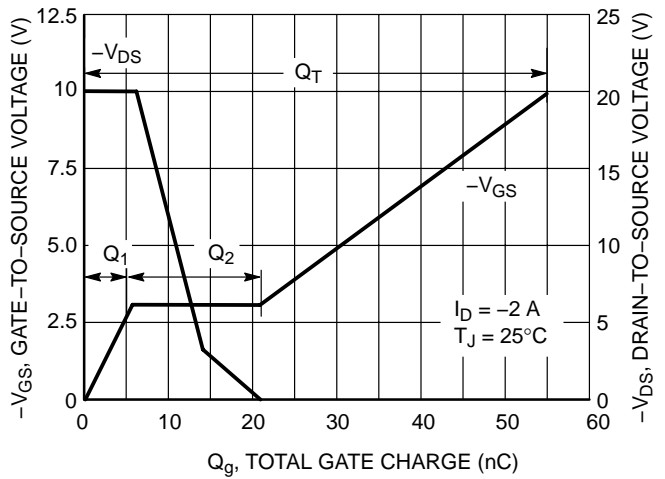


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

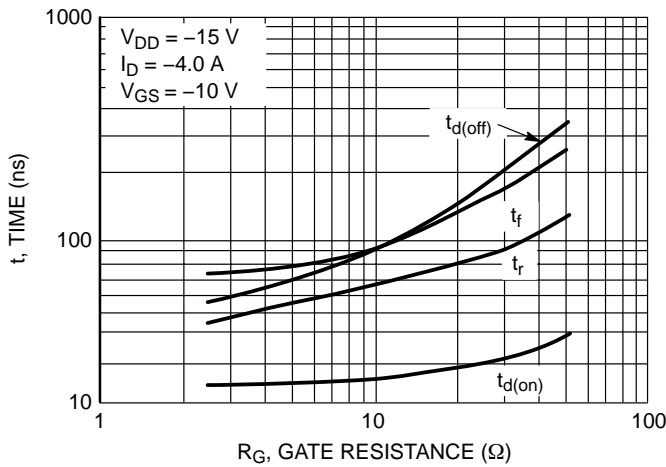


Figure 9. Resistive Switching Time Variation versus Gate Resistance

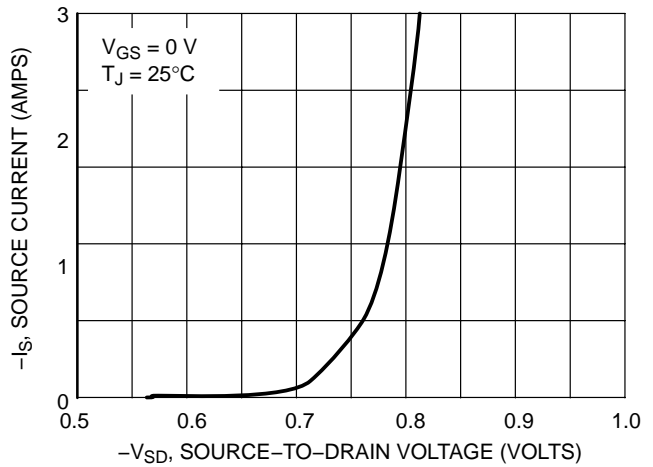
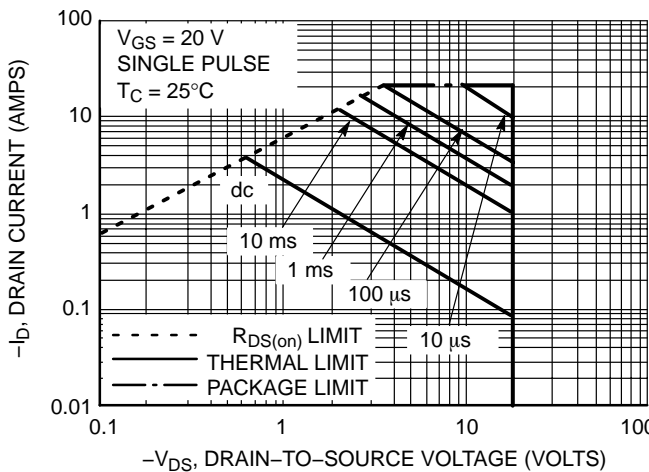


Figure 10. Diode Forward Voltage versus Current



Mounted on 2"sq. FR4 board (1"sq. 2 oz. Cu 0.06" thick single sided) with on die operating, 10 s max.

Figure 11. Maximum Rated Forward Biased Safe Operating Area

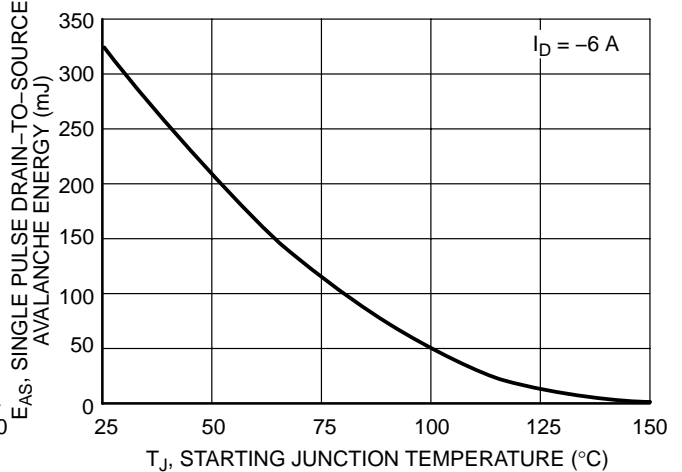


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

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## TYPICAL ELECTRICAL CHARACTERISTICS

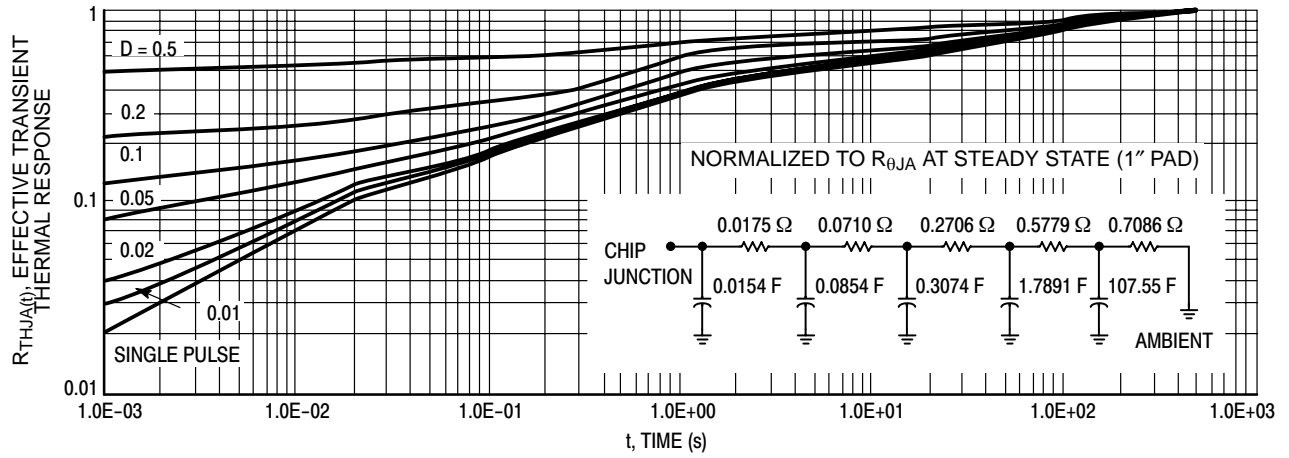


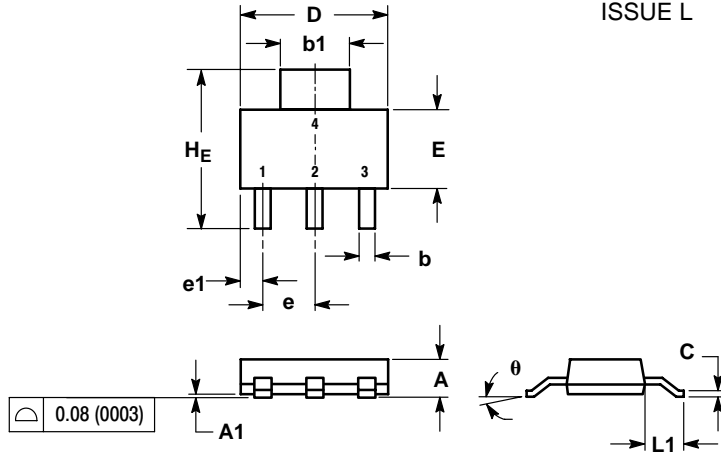
Figure 13. FET Thermal Response

# NTF5P03T3

## PACKAGE DIMENSIONS

SOT-223 (TO-261)  
CASE 318E-04  
ISSUE L

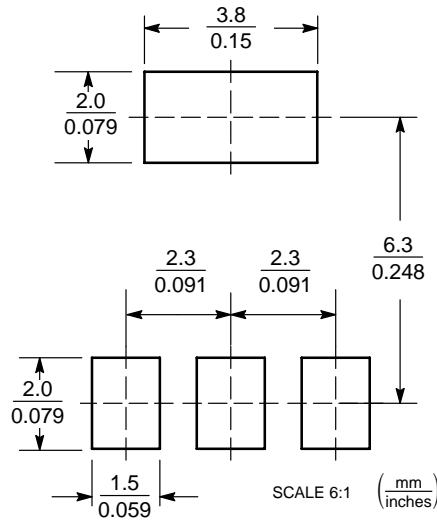
- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: INCH.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
H	6.70	7.00	7.30	0.264	0.276	0.287
theta	0°	-	10°	0°	-	10°

- STYLE 3:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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